

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3735	(165/80:2-80:3,185).CCLS.	USPAT	OR	OFF	2005/08/04 09:55
L2	12972	((257/706-707,712-713) or (361/704-710,714-721) or (428/119,122,209,125,332,339)).CCLS.	USPAT	OR	OFF	2005/08/04 09:57
L3	0	"processor chip" and substrate and "thermal interface device" and "first metal layer" and "second metal layer" and carbon and ("integrated circuit package" or IC).dlm.	US-PGPUB	OR	ON	2005/08/04 10:03